



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-DS3800HLNC

Test Procedure for a DS3800HLNC card

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

| REV. | DESCRIPTION | SIGNATURE | REV. DATE |
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| DATE 7/15/2011 | DATE | DATE | DATE 7/15/2011 |

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1. SCOPE

1.1 This is a functional testing procedure for a DS3800HLNC.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

| Qty | Reference # | Description |
|-----|-------------|--|
| 1 | | FVE Module |
| 1 | | See equipment section in the following page scanned test |
| | | |

6. Testing Process

6.1 Page 1 of scanned HLNC instruction

9.0 HLNC FUN FUNCTIONAL TEST INSTRUCTIONS9.1 SCOPE

THIS DOCUMENT DESCRIBES THE SETUP AND FUNCTIONAL TEST PROCEDURE FOR PWB DS3800HLNC. PRIOR TO PERFORMING THIS TEST, THE PWB SHOULD HAVE PASSED TEST ON THE 2270.

9.2 SPECIAL TEST EQUIPMENT

1. FUNCTIONAL TEST MODULE: FVE
2. TEST SUPPORT CARDS AND SETUP. (NOTE: HLNC IN 2D OR 2F OR BOTH CAN BE BOARD UNDER TEST. USE SAME PROCEDURE FOR TESTING EITHER ONE BOARD OR TWO BOARDS AT A TIME.)

| | | |
|---------|--------|---|
| SLOT 2B | HMPJ | ROM SET "SD_00_MONITOR_RAM_TC" |
| SLOT 2D | HLNC | PROM "PSP3815PLNC01AB" IN SOCKET U27 PROM "PSP3815PLNC02AB" IN SOCKET U28 J1-J3, J5-J9 "F" J4 "T" J10-J13 "A" |
| SLOT 2C | HLND | J1 "T" J2-J6 "F" J9 IN |
| SLOT 2F | HLNC | PROM "PSP3815PLNC01AB" IN SOCKET U27 PROM "PSP3815PLNC02AB" IN SOCKET U28 J1-J3, J6-J9 "F" J4, J5 "T" J10-J13 "A" |
| SLOT 2E | HLND | J1, J2 "T" J3-J6 "F" J9 IN |
| | HMAC#1 | J41-J43 "T" J61-J63 "T" J5B, D "GND" J5C, E OPEN |
| | HMAC#2 | J41-J43 "T" J61-J63 "T" J5B, D "GND" J5C, E OPEN |

9.3 POWER SUPPLY REQUIREMENTS

THIS TEST IS WRITTEN ASSUMING THE USE OF POWER SUPPLY TYPE DS3820PSLA1A1A.

9.4 INITIAL SETUP

1. PLUG CARDS IN MODULE PER SECTION 9.2
2. CABLE INTERCONNECTIONS.
CABLE TYPE FROM TO

6.2 Page 2 of scanned HLNC instruction

| | | |
|---------------|----------------|--------------|
| POWER CABLE | PVE-JA | PS-JA |
| POWER CABLE | HMACH1-JG | PS-JF |
| POWER CABLE | HMACH2-JG | PS-JE |
| 20 PIN RIBBON | HLND 2C-JA | HMACH1-JA |
| 20 PIN RIBBON | HLND 2E-JA | HMACH2-JA |
| 50 PIN RIBBON | HLND 2C | HLNC 2D |
| 50 PIN RIBBON | HLND 2E | HLNC 2F |
| THRAA CABLE | HMACH2-JE | HMACH1-JB |
| THRAA CABLE | HMACH1-JE | HMACH2-JB |
| * RS232 CABLE | COMPUTER TERM. | HMPJ SLOT 2B |

* USE NULL MODEM (DS3800HMAA) ON HMPJ END OF CABLE.
JUMPER IN SPDE POSITION, JA CONNECTOR CONNECTED TO HMPJ.

9.0 TEST DEFINITIONS AND SPECIAL NOTES

NONE

9.0 TEST PROCEDURE

Each HLND connected to a HMAA
Put HMAA in 2D (2F+2E connected) (2D+2C connected)
HLNC
HMAA = slot 2B

1. APPLY POWER.
2. AFTER CR2 COMES ON ON THE HMPJ, TYPE "BB" (WR80.)
3. TYPE "SA4000," (ADDA-) *SW4000, A55A-7FF7*
4. TYPE "/FF7" THEN [RETURN] AND WATCH FOR THE FOLLOWING TO OCCUR AT THE HLNC IN SLOT 2D.
 - IMOK LED ON (AFTER ABOUT 10 SECONDS).
 - DIAG LED ON FOR ABOUT 5 SECONDS AND THEN GOES OUT.
 - AFTER DIAG LED GOES OUT, CONFIG LED COMES ON AND BLINKS.
 - IMOK LED REMAINS ON
5. TYPE "SA0000," (ADDA) *SC4000, A55A-7FF7*
6. TYPE "/FF7" THEN [RETURN] AND THEN VERIFY THAT AFTER APPROXIMATELY 5 SECONDS THE IMOK LED'S ON BOTH HLNC'S ARE ON. (OTHER HLNC LED'S OFF)
7. REMOVE POWER.
8. IF CARDS CAME INTO TEST WITHOUT TEST ROMS THEN REMOVE TEST PROM FROM HLNC UNDER TEST (SLOT 2C). (OR BOTH HLNC'S IF TWO CARDS TESTED AT ONCE.)

END OF TEST

TEST INSTRUCTION REVISION STATUS

| REV | INIT | DESCRIPTION OF CHANGE | DATE COMPLETE |
|-----|------|--------------------------------|---------------|
| 0 | REV | FIRST MADE FOR DS3800HLNC DATA | 28-APR-80 |
| 1 | REV | VARIOUS CHANGES PER DB | 03-MAY-80 |
| 2 | DB | REMOVED REFERENCES TO HLNC | 20-SEP-80 |

6.3 ***TEST COMPLETE***

7. Attachments

7.1 None at this time